

SOT874-1

plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body 3.3 x 3.3 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON8
Package type industry code	HVSON8
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	29-11-2005

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		3.2	-	3.3	3.4	mm
E	package width		3.2	-	3.3	3.4	mm
A	seated height		[tbd]	-	0.85	1	mm
A ₂	package height		[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination		-	-	8	-	

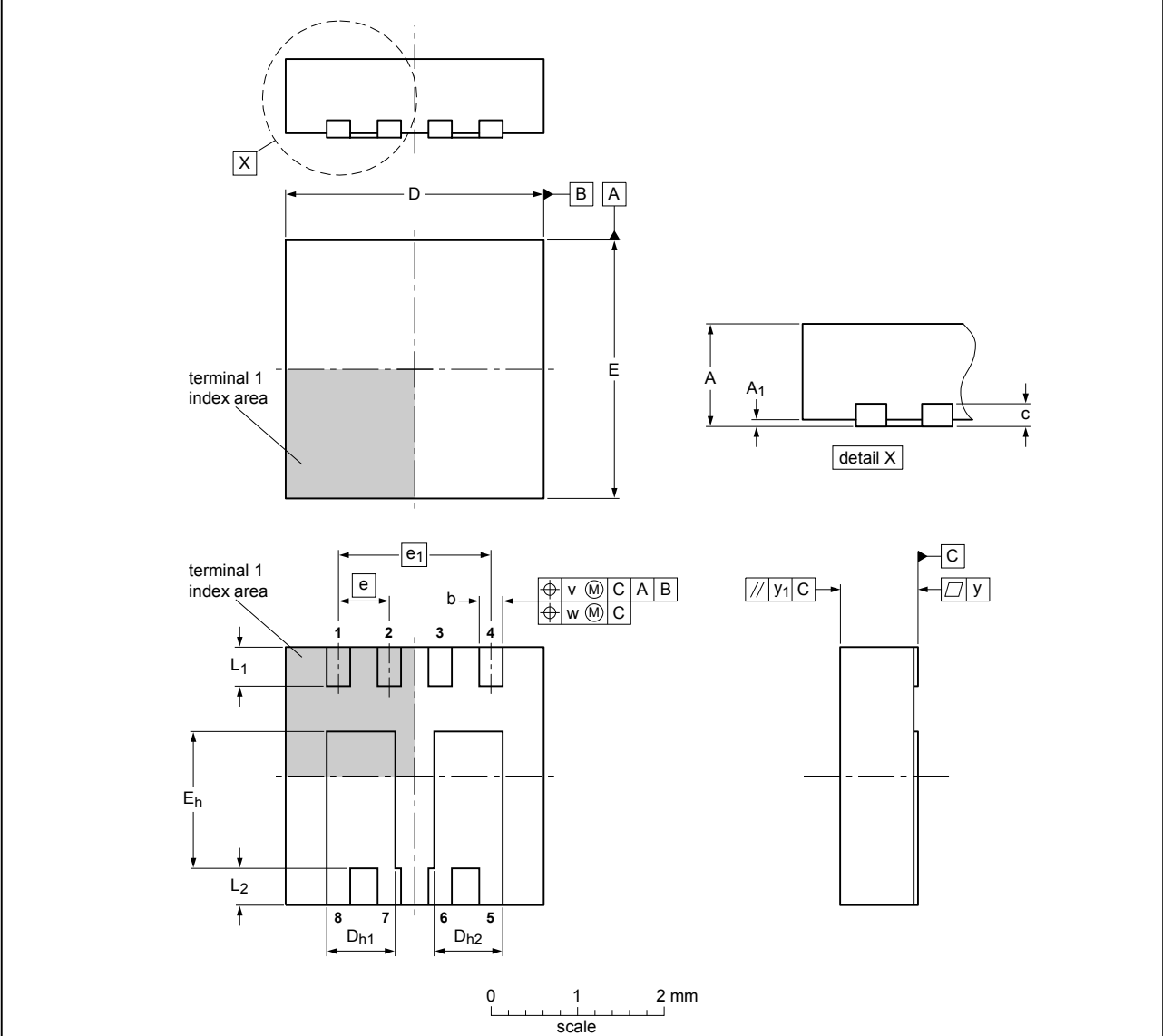


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2. Package outline

HVSON8: plastic thermal enhanced very thin small outline package; no leads;
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DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ max.	A ₁	b	c	D ⁽¹⁾	D _{h1}	D _{h2}	E ⁽¹⁾	E _h	e	e ₁	L ₁	L ₂	v	w	y	y ₁
mm	1	0.05 0.00	0.35 0.25	0.2	3.4 3.2	0.93 0.83	0.93 0.83	3.4 3.2	1.85 1.65	0.65	1.95	0.55 0.43	0.52 0.42	0.1	0.05	0.05	0.1

Note
1. Plastic or metal protrusions of 0.075 mm maximum per side are not included

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT874-1	---	---	---			05-11-09 05-11-29

Fig. 1. Package outline HVSON8 (SOT874-1)

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3. Legal information

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